upplier Information ompany name* Company unique ID Unique ID Authority seemi Ontact Name Title - Contact Phone - Contact* Phone - Contact* Email - Contact* Email - Contact* Email - Contact* Product Env-Stewards Unique ED Authority Response Date* 2025-06-08 Title - Contact Phone - Contact* Email - Contact* Product Env-Stewards Orduct Env-Stewards Product Enviro Compliance NA Product Env-Stewards NA Product-Env-Stewards UOM Unit Ty Effective Date Version Manufacturing Site Weight* UOM Unit Ty Insufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy Insufacturing Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy Insufacturing Peak Process Body Temperature Number of Reflow Cycles Matter Tin (Sn) - annealed CU Alloy Insufacturing Peak Process Body Temperature Number of Reflow Cycles Matter Tin (Sn) - annealed CU Alloy Insufacturing Peak Temperature Number of Reflow Cycles Anter Tin (Sn) - annealed CU Alloy Insufacturing Peak Temperature Number of Reflow Cycles Anter Tin (Sn) - annealed CU Alloy Insufacturing Peak Process Body Temperature Number of Reflow Cycles Anter Tin (Sn) - annealed CU Alloy Insufacturing Peak Temperature Number of Reflow Cycles Anter Tin (Sn) - annealed CU Alloy Insufacturing Peak Temperature Number of Reflow Cycles Anter Tin (Sn) - annealed CU Alloy Insufacturing Peak Temperature Number of Reflow Cycles Anter Tin (Sn) - annealed CU Alloy Insufacturing Peak Process Body Temperature Number of Reflow Cycles Anter Tin (Sn) - annealed CU Alloy Insufacturing Peak Temperature Number of Reflow Cycles Anter Tin (Sn) - annealed CU Alloy Insufactur	IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
mpany name* Company unique ID Unique ID Authority Response Date* 2025-06-08 Intel - Contact* Product Env-Stewards Product Env-Steward	752-21.1											als and Mf	fg Information	on	
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Title - Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Representative* Requester Item Number Reflective Date Representative* Remail - Representative* Remail - Representative* Reproduct-Env-Stewards @onsemi.com Regulater Item Number Representative* Representative* Representative* Remail - Representative* Representative* Remail - Representative* Reproduct-Env-Stewards @onsemi.com Requester Item Number Reflow Cycles Representative* Representative* Representative* Representative* Requester Item Number Representation R	Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
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Requester Item Number	Authorized Representative*			Title - Representative			F	Phone - Representative*				Email - Representative*			
SIGHE SR SOD323HE GPPN 1A 400V 2025-06-08 TSCBE 6.000001 mg Each Insufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles and Seconds 1	Product-Env-Steward	ds		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
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		no at neals temperature	duning cal	doring is 10 2	10 seconds										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead). Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
	Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature R		,									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	0.22002	mg	В	Nickel (Ni)	7440-02-0		0.0001	mg
			Supplier	Copper (Cu)	7440-50-8		0.2199	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0001	mg
Die	0.67998	mg	Supplier	Silicon (Si)	7440-21-3		0.612	mg
			В	Nickel (Ni)	7440-02-0		0.0044	mg
			Supplier	Gold (Au)	7440-57-5		0.001	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.0626	mg
Die Attach Solder	0.250021	mg	Supplier	Silver (Ag)	7440-22-4		0.0063	mg
			A	Lead (Pb)	7439-92-1	7a	0.2313	mg
			Supplier	Tin (Sn)	7440-31-5		0.0125	mg
Lead Frame	1.39002	mg	Supplier	Iron (Fe)	7439-89-6		0.0014	mg
			Supplier	Copper (Cu)	7440-50-8		1.3882	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0004	mg
Mold Compound-Black	3.25998	mg		Metal Hydroxide	proprietary data		0.1141	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.2608	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0163	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		2.608	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.2608	mg
Plating	0.19998	mg	Supplier	Tin (Sn)	7440-31-5		0.2	mg